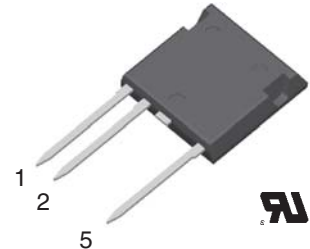
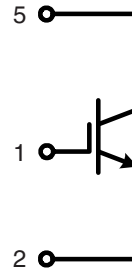


# High Voltage IGBT

in High Voltage  
ISOPLUS i4-PAC™

$I_{C25} = 32 \text{ A}$   
 $V_{CES} = 2500 \text{ V}$   
 $V_{CE(sat)} = 3.2 \text{ V}$   
 $t_f = 250 \text{ ns}$



## IGBT

Symbol	Conditions	Maximum Ratings	
$V_{CES}$	$T_{VJ} = 25^\circ\text{C to } 150^\circ\text{C}$	2500	V
$V_{GES}$		$\pm 20$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	32	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	19	A
$I_{CM}$	$V_{GE} = \pm 15 \text{ V}; R_G = 47 \Omega; T_{VJ} = 125^\circ\text{C}$	70	A
$V_{CEK}$	RBSOA, Clamped inductive load; $L = 100 \mu\text{H}$	1200	V
$P_{tot}$	$T_C = 25^\circ\text{C}$	250	W

## Features

- High Voltage IGBT
  - substitute for high voltage MOSFETs with significantly lower voltage drop and comparable switching speed
  - substitute for high voltage thyristors with voltage control of turn on & turn off
  - substitute for electromechanical trigger and discharge relays
- ISOPLUS i4-PAC™ high voltage package
  - isolated back surface
  - enlarged creepage towards heatsink
  - enlarged creepage between high voltage pins
  - application friendly pinout
  - high reliability
  - industry standard outline
  - UL registered E72873

Symbol	Conditions	Characteristic Values ( $T_{VJ} = 25^\circ\text{C}$ , unless otherwise specified)			
		min.	typ.	max.	
$V_{CE(sat)}$	$I_C = 19 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		3.2 4.7	V V	
$V_{GE(th)}$	$I_C = 1 \text{ mA}; V_{GE} = V_{CE}$	5		8 V	
$I_{CES}$	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$		0.2	0.15 mA mA	
$I_{GES}$	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			500 nA	
$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$ $E_{on}$ $E_{off}$	Inductive load, $T_{VJ} = 125^\circ\text{C}$ $V_{CE} = 1500 \text{ V}; I_C = 19 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 47 \Omega$		100 50 600 250 15 30	ns ns ns ns mJ mJ	
$C_{ies}$ $C_{oes}$ $C_{res}$		$V_{CE} = 25 \text{ V}; V_{GE} = 0 \text{ V}; f = 1 \text{ MHz}$		2.28 103 43	nF pF pF
$Q_{Gon}$			$V_{CE} = 1500 \text{ V}; V_{GE} = 15 \text{ V}; I_C = 19 \text{ A}$	142	nC
$R_{thJC}$					0.5 K/W

## Applications

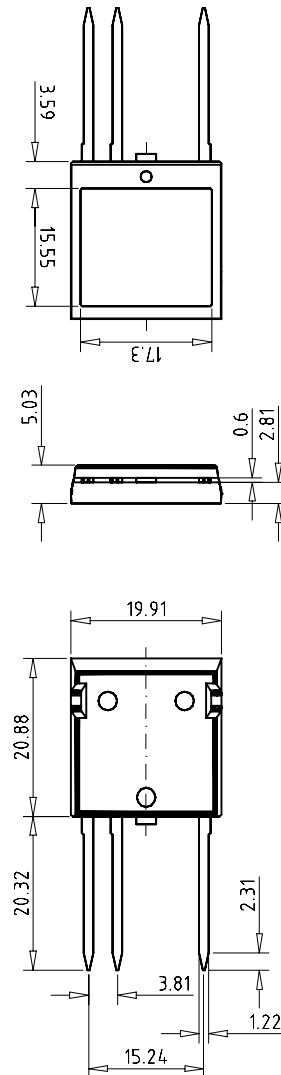
- switched mode power supplies
- DC-DC converters
- resonant converters
- laser generators, x ray generators
- discharge circuits

### Component

Symbol	Conditions	Maximum Ratings	
$T_{VJ}$		-55...+150	°C
$T_{stg}$		-55...+125	°C
$V_{ISOL}$	$I_{ISOL} \leq 1 \text{ mA}; 50/60 \text{ Hz}$	2500	V~
$F_C$	mounting force with clip	20...120	N

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
$d_S, d_A$	C pin - E pin	7.0		mm
$d_S, d_A$	pin - backside metal	5.5		mm
$R_{thCH}$	with heatsink compound		0.15	K/W
<b>Weight</b>			9	g

### Dimensions in mm (1 mm = 0.0394")



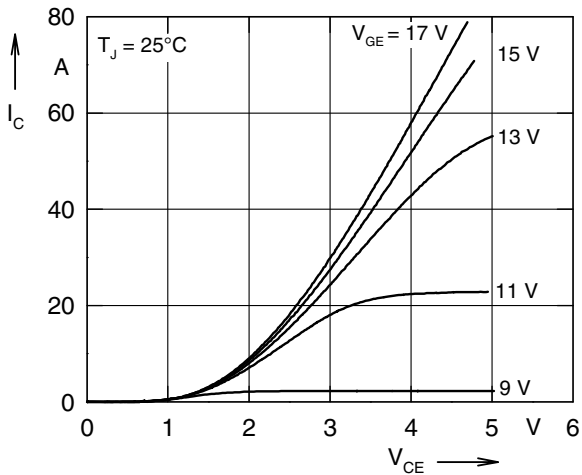


Fig. 1 Typ. Output Characteristics

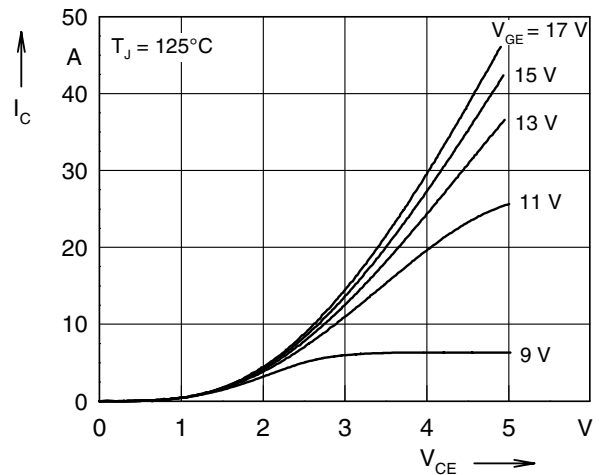


Fig. 2 Typ. Output Characteristics

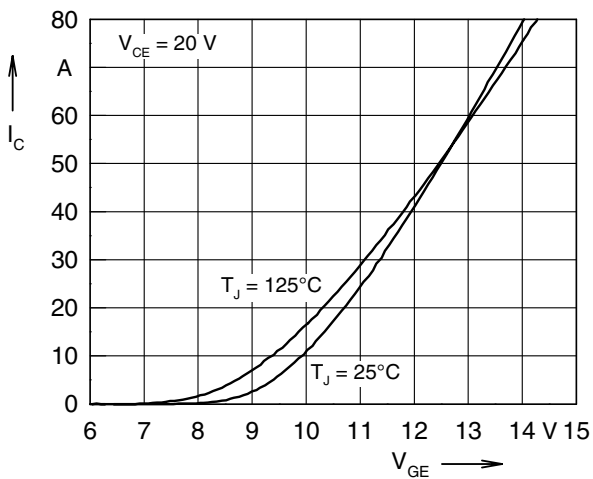


Fig. 3 Typ. Transfer Characteristics

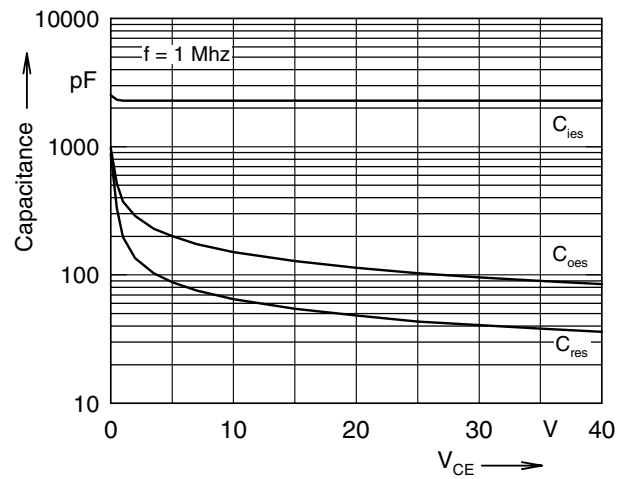


Fig. 4 Capacitance curves

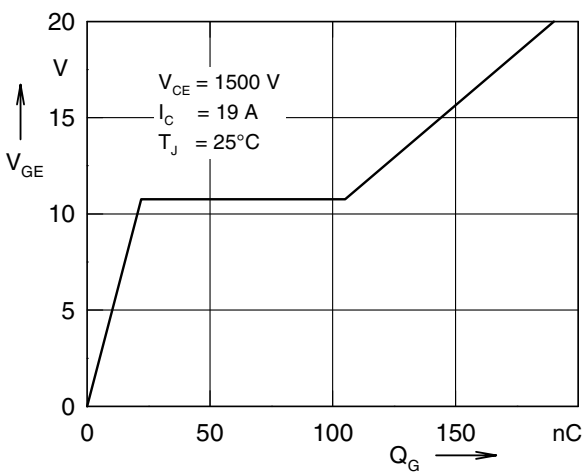


Fig. 5 Typ. Gate Charge characteristics

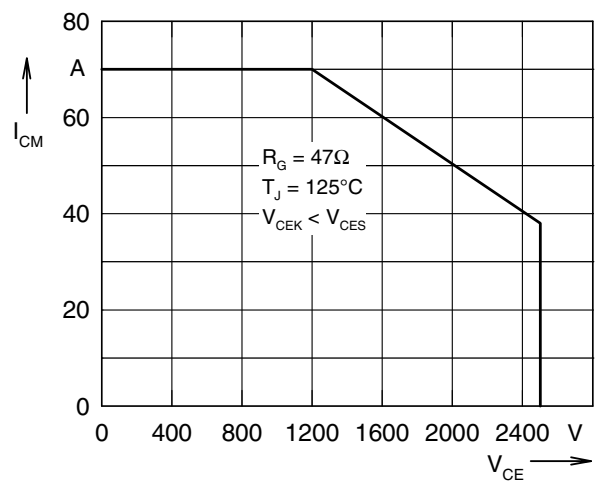


Fig. 6 Reverse Biased Safe Operating Area RBSOA

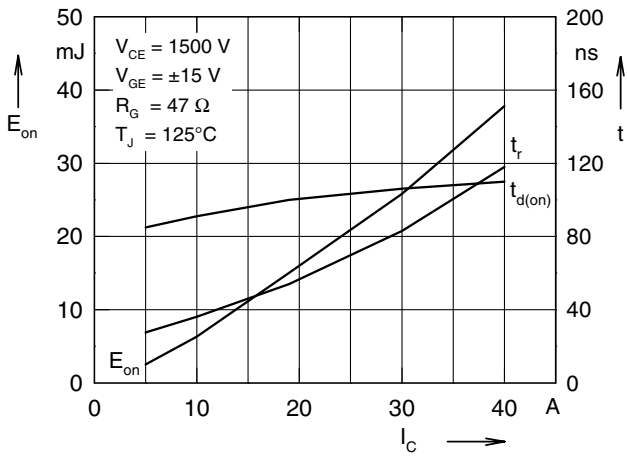


Fig. 7 Typ. turn on energy and switching times versus collector current

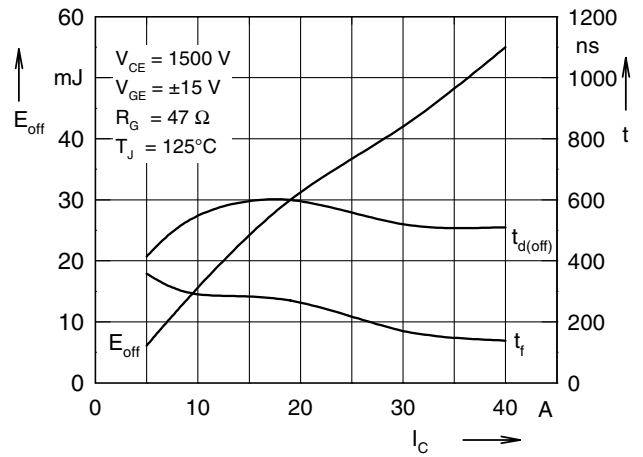


Fig. 8 Typ. turn off energy and switching times versus collector current

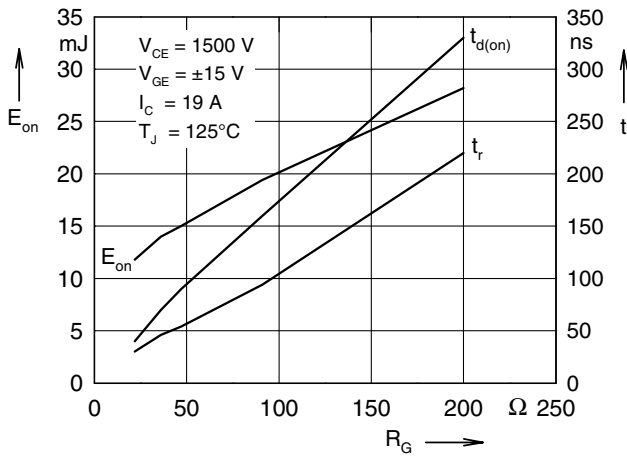


Fig. 9 Typ. turn on energy and switching times versus gate resistor

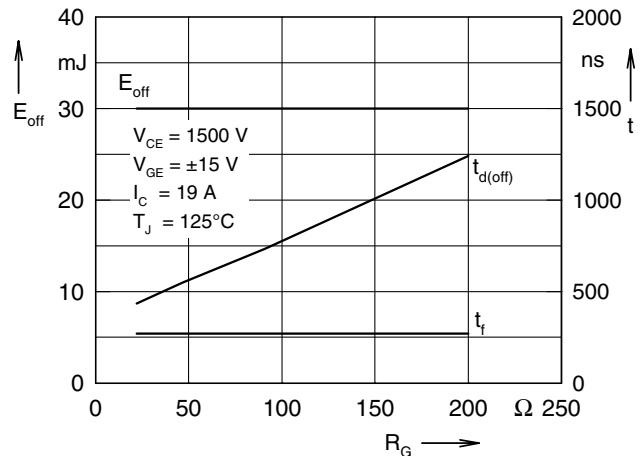


Fig. 10 Typ. turn off energy and switching times versus gate resistor

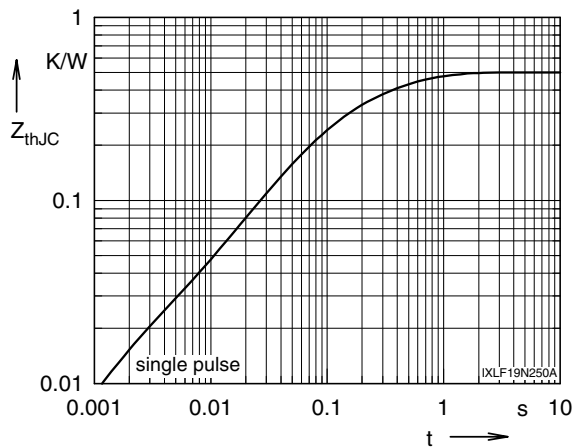


Fig. 11 Typ. transient thermal impedance

This datasheet has been download from:

[www.datasheetcatalog.com](http://www.datasheetcatalog.com)

Datasheets for electronics components.